

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Currently Amended) An interconnection element comprising:
a first element material adapted to be coupled to a substrate; and
a second different element material coupled to the first element material,
wherein one of the first element material and the second element material comprises a
material having a property that may be transformed in response to an external stimulus
applied to one of the first and second element materials such that upon transformation,
a geometric shape of the interconnection element is modified to a shape suitable for use
as an interconnection element, and wherein the interconnection element has an overall
thickness greater than 1 μ m.
2. (Original) The interconnection element of claim, wherein the interconnection
element is of a size suitable for directly contacting a semiconductor device.
3. (Original) The interconnection element of claim 1, wherein a transformation
of the one of the first element material and the second element material is irreversible.
4. (Previously presented) The interconnection element of claim 1, wherein the
property is such that a first volume of one of the first element material and the second
element material is adapted to be transformed to a different second volume.
5. (Original) The interconnection element of claim 4, wherein the first element
material and the second element material are arranged in a configuration such that the
second element material overlies the first element material and the first volume of the
second element material is greater than the second volume.

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6. (Original) The interconnection element of claim 4, wherein the first element material is thermally stable and a transformation of the second element material from the first volume to the second volume is a result of exposing the second element material to heat.
7. (Previously presented) The interconnection element of claim 6, wherein the second volume comprises about 90 percent of the first volume of the second element material.
8. (Original) The interconnection element of claim 1, wherein each of the first element material and the second element material have a transformable property.
9. (Previously Presented) The interconnection element of claim 1, wherein at least one of the first element material and the second element material are introduced by plating.
10. (Original) The interconnection element of claim 1, wherein at least one of the first element material and the second element material are introduced by sputtering.
11. (Original) The interconnection element of claim 1, wherein at least one of the first element material and the second element material are introduced by electroless plating.
12. (Original) The interconnection element of claim 3, wherein the first element material comprises palladium or its alloy.
13. (Previously Presented) The interconnection element of claim 4, wherein the first element material is an alloy comprising palladium/cobalt and an activation layer comprises one of copper and nickel.
14. (Original) The interconnection element of claim 13, wherein the second element material further comprises nickel.

15. (Original) The interconnection element of claim 13, wherein the second element material comprises a nickel alloy.
16. (Original) The interconnection element of claim 1, wherein the one of the first element material and the second element material comprises a shape memory alloy.
17. (Original) The interconnection element of claim 16, wherein the second element material comprises the shape memory alloy and overlies the first element material.
18. (Previously Presented) The interconnection element of claim 1, wherein the property is a stress and the transformation reduces the magnitude of the stress of the material.
19. (Previously Presented) The interconnection element of claim 18, wherein the first element material comprises the material having the property and the second element material has a tensile stress, wherein upon transformation, the deformation comprises a response to the tensile stress of the second element material.
20. (Original) The interconnection element of claim 19, wherein the second element material is thermally stable and a transformation of the first element material is a result of exposing the first element material to heat.
21. (Previously Presented) The interconnection element of claim 18, wherein the first element material comprises the material having the property and the second element material has a compressive stress, wherein upon transformation, the deformation comprises a response to the compressive stress of the second element material.
- 22-82. (Canceled)
83. (New) The interconnection element of claim 1, wherein the overall thickness is between 1 and 500 μm .

84. (New) The interconnection element of claim 1, wherein the overall thickness is greater than 25 μm .
85. (New) The interconnection element of claim 1, wherein the overall thickness is about 28 μm .
86. (New) The interconnection element of claim 1, wherein the first element material has a thickness between 1 and 3 μm .
87. (New) The interconnection element of claim 1, wherein the first element material has a thickness of about 5 μm and the second element material has a thickness between about 3 and 6 μm .
88. (New) The interconnection element of claim 1, wherein the first element material has a thickness between about 12 and 25 μm .